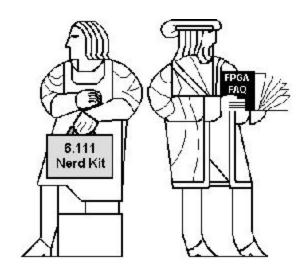
6.111 Lecture 10

Today: Memories

- 1.Static RAMs
- 2. Interfacing: Bus & Protocol
- 3. Synchronous Memories
- 4. EPROMs and DRAMs
- 5. Memory Mapped Peripherals



Acknowledgement: Nathan Ickes, Rex Min

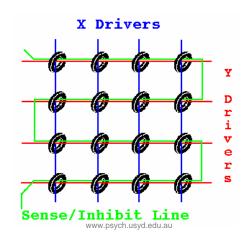
J. Rabaey, A. Chandrakasan, B. Nikolic, "Digital Integrated Circuits: A Design Perspective" Prentice Hall, 2003 (Chapter 10)

Memories of a Digital World

Why need memories? State machines...

Memories:

- Flip Flips, Registers, FIFO (first-in-first-out)
- Core memory!
- Random Access (static/dynamic, read/write)
- Slow / Non-volatile (hard drive/eeprom/eprom)
- Content-addressable
- Concept of a BUS and use of TRISTATE!



Key Design Metrics:

- 1. Memory Density (number of bits/μm²) and Size
- 2. Access Time (time to read or write) and Throughput
- 3. Power Dissipation

Memory Classification & Metrics

Read-Write Memory		Non-Volatile Read-Write Memory	Read-Only Memory (ROM)
Random Access	Non-Random Access	EPROM E ² PROM	Mask-Programmed
SRAM DRAM	FIFO LIFO	FLASH	

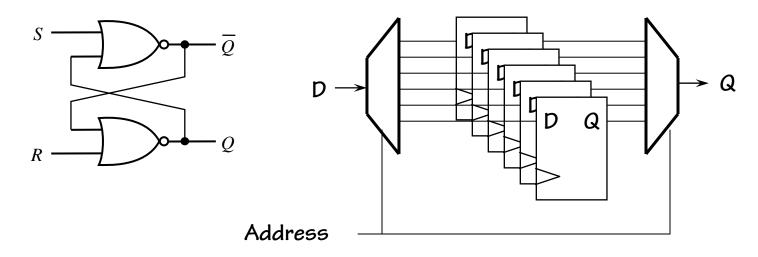
Key Design Metrics:

- 1. Memory Density (number of bits/μm²) and Size
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1. Static RAMs: Latch Based Memory

Set Reset Flip Flop

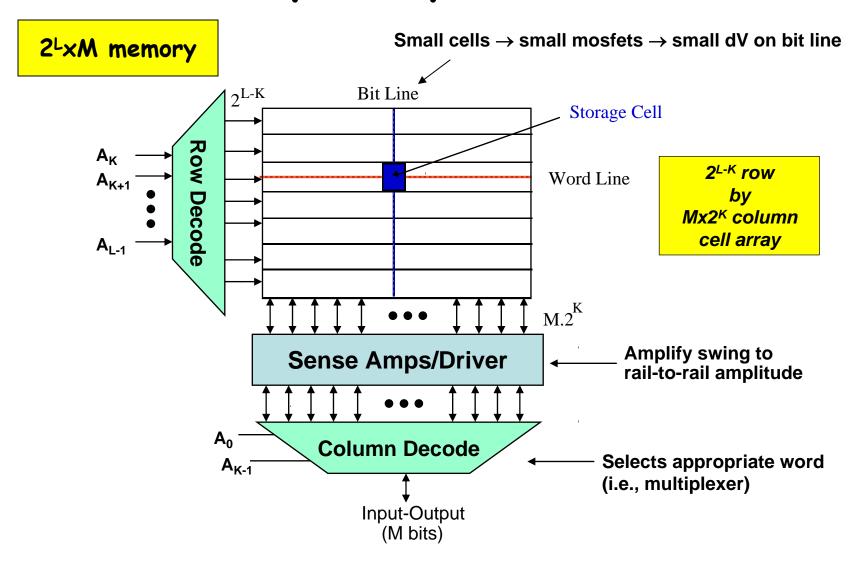
Register Memory



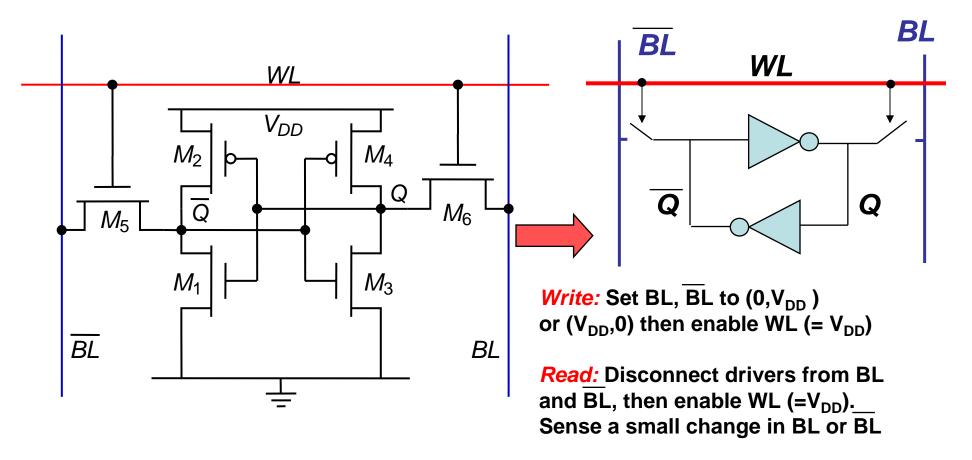
- Works fine for small memory blocks (e.g., small register files)
- Inefficient in area for large memories
- Density is the key metric in large memory circuits

How do we minimize cell size?

Memory Array Architecture

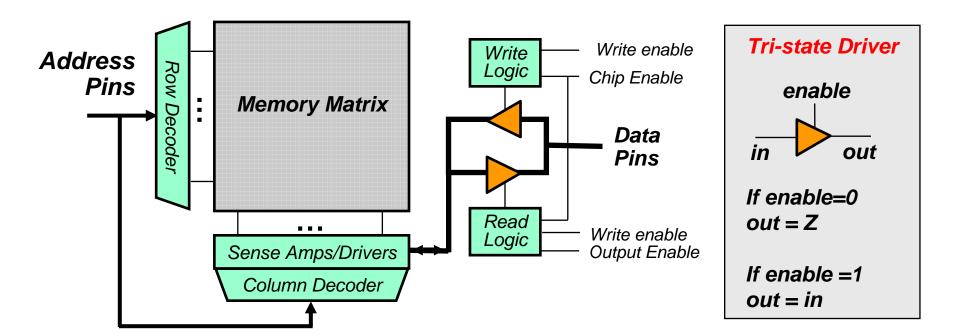


Static RAM (SRAM) Cell (The 6-T Cell)



- State held by cross-coupled inverters (M1-M4)
- Retains state as long as power supply turned on
- Feedback must be overdriven to write into the memory

2. Using External Memory Devices



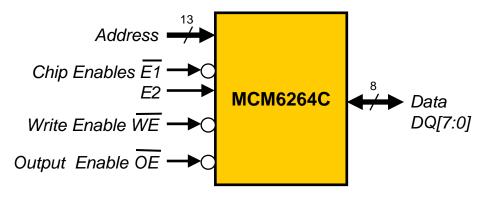
- Address pins drive row and column decoders
- Data pins are bidirectional: shared by reads and writes

Concept of "Data Bus"

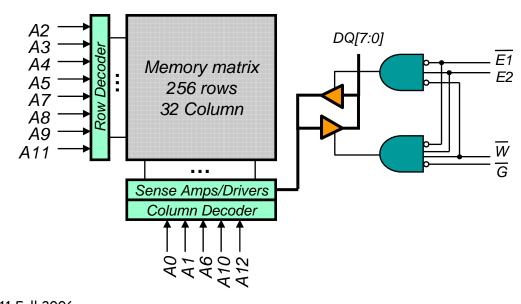
- Output Enable gates the chip's tristate driver
- Write Enable sets the memory's read/write mode
- Chip Enable/Chip Select acts as a "master switch"

MCM6264C 8K x 8 Static RAM

On the outside:



On the inside:



Same (bidirectional) data bus used for reading and writing

Chip Enables ($\overline{E1}$ and E2)

E1 must be low and E2 must be high to enable the chip

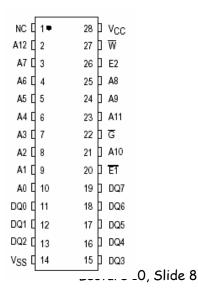
Write Enable (WE)

When low (and chip enabled), values on data bus are written to location selected by address bus

Output Enable (OE or G)

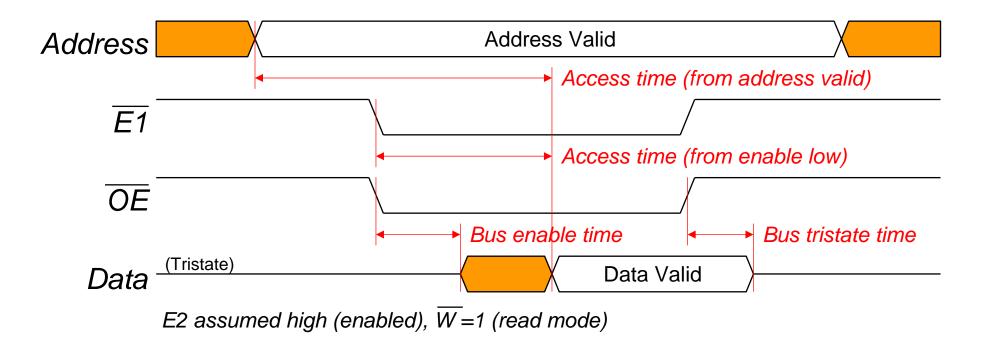
When low (and chip is enabled), data bus is driven with value of selected memory location

Pinout



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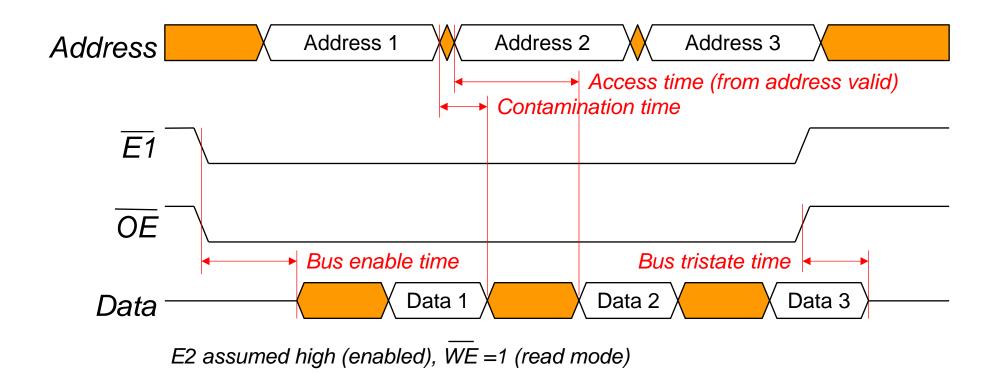
Reading an Asynchronous SRAM



- Read cycle begins when all enable signals (E1, E2, OE)
 are active
- Data is valid after read access time
 - Access time is indicated by full part number: MCM6264CP-12 → 12ns
- Data bus is tristated shortly after OE or E1 goes high

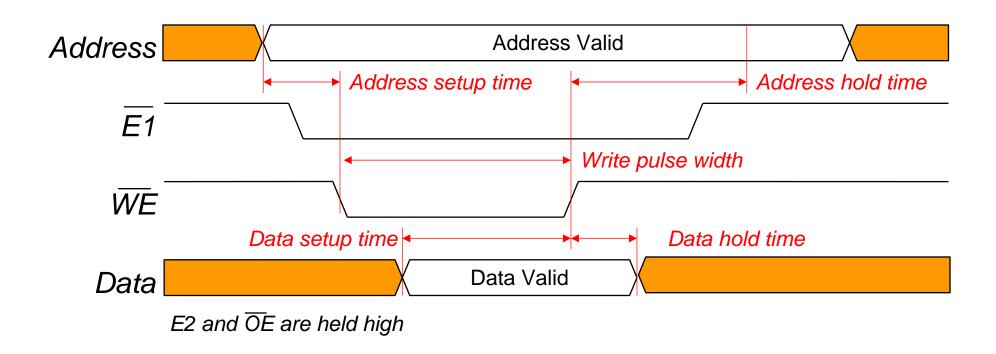
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Address Controlled Reads



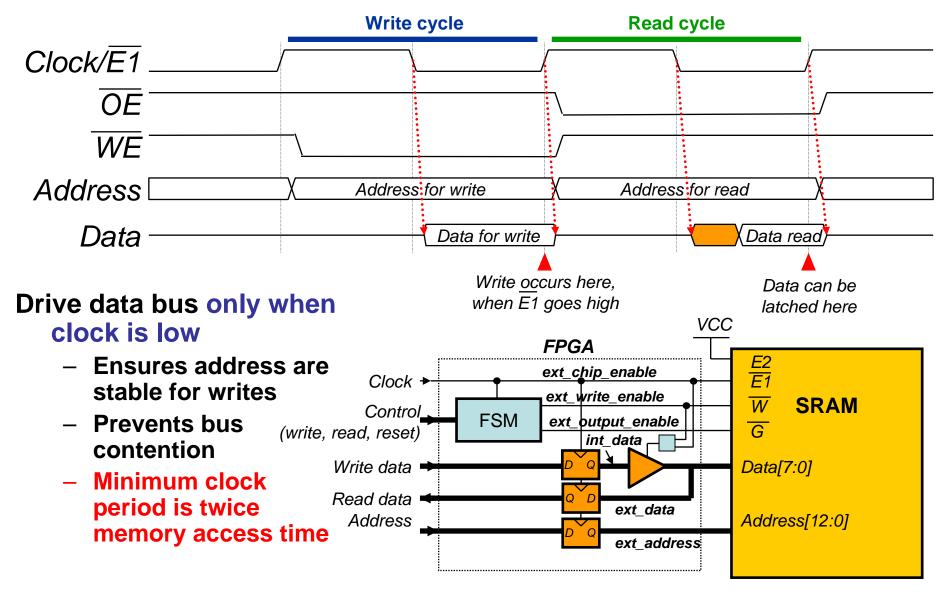
- · Can perform multiple reads without disabling chip
- · Data bus follows address bus, after some delay

Writing to Asynchronous SRAM

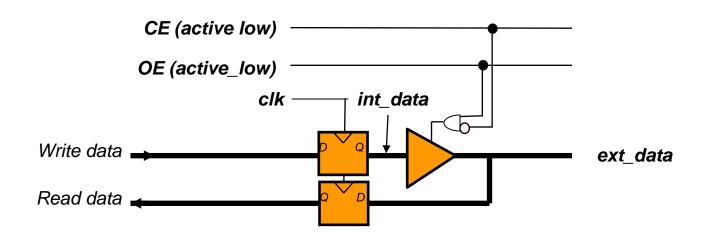


- Data latched when WE or E1 goes high (or E2 goes low)
 - Data must be stable at this time
 - Address must be stable before WE goes low
- Write waveforms are more important than read waveforms
 - Glitches to address can cause writes to random addresses!

Sample Memory Interface Logic



Tristate Data Buses in Verilog

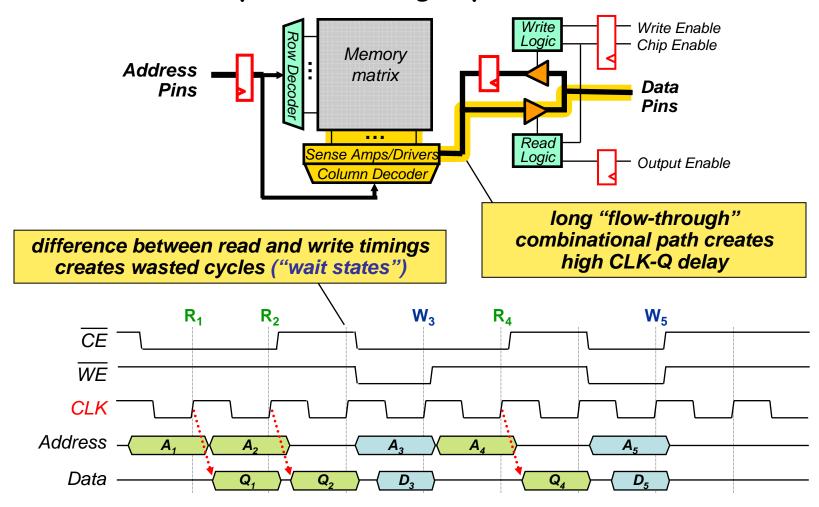


```
output CE,OE; // these signals are active low
inout [7:0] ext_data;
reg [7:0] read_data,int_data
wire [7:0] write_data;
always @ (posedge clk) begin
  int_data <= write_data;
  read_data <= ext_data;
end

// Use a tristate driver to set ext_data to a value
assign ext_data = (~CE & OE) ? int_data : 8'hZZ;</pre>
```

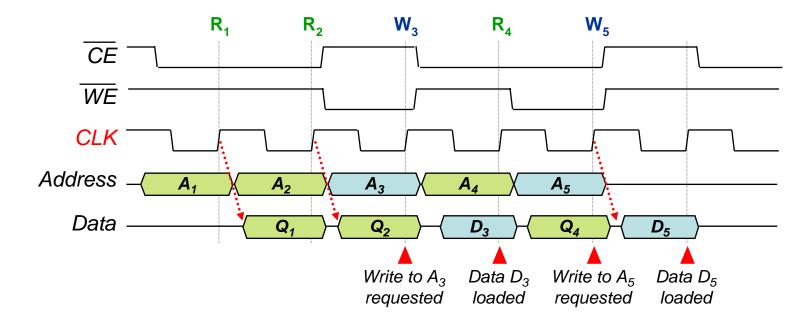
3. Synchronous SRAM Memories

 Clocking provides input synchronization and encourages more reliable operation at high speeds



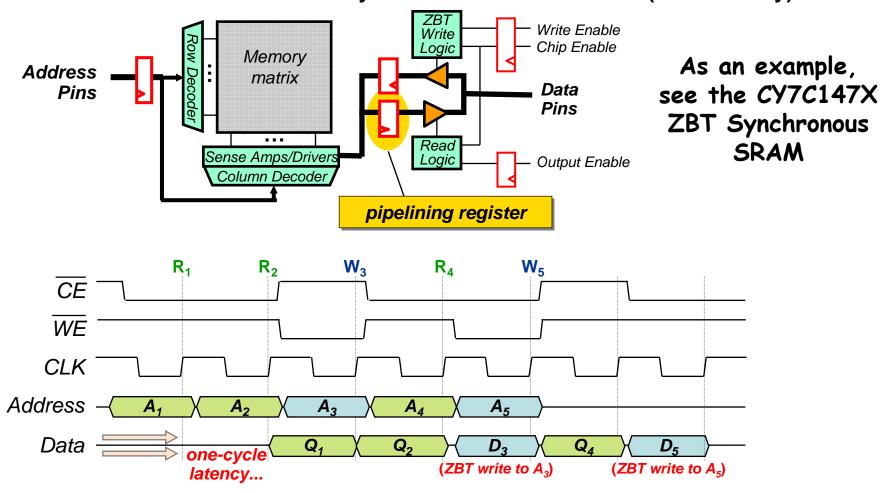
ZBT Eliminates the Wait State

- The wait state occurs because:
 - On a read, data is available after the clock edge
 - On a write, data is set up before the clock edge
- ZBT ("zero bus turnaround") memories change the rules for writes
 - On a write, data is set up after the clock edge (so that it is read on the following edge)
 - Result: no wait states, higher memory throughput



Pipelining Allows Faster CLK

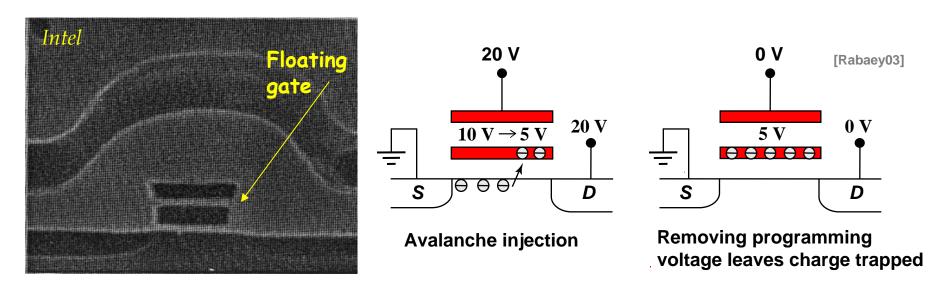
- Pipeline the memory by registering its output
 - Good: Greatly reduces CLK-Q delay, allows higher clock (more throughput)
 - Bad: Introduces an extra cycle before data is available (more latency)



4. EPROMs and DRAMs

EEPROM - The Floating Gate Transistor

Electrically Erasable Programmable Read-Only Memory



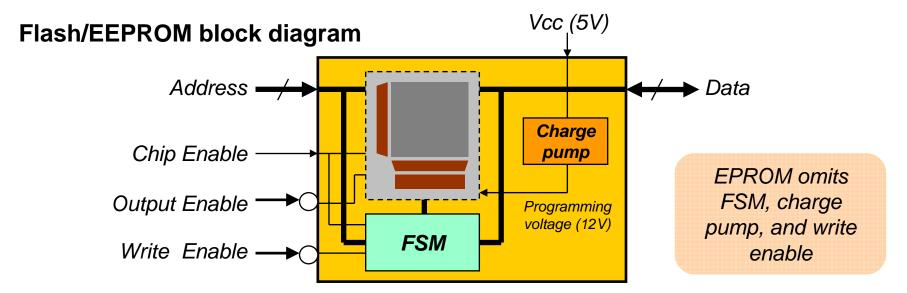
This is a non-volatile memory (retains state when supply turned off)

Usage: Just like SRAM, but writes are much slower than reads (write sequence is controlled by an FSM internal to chip)

Common application: configuration data (serial EEPROM)

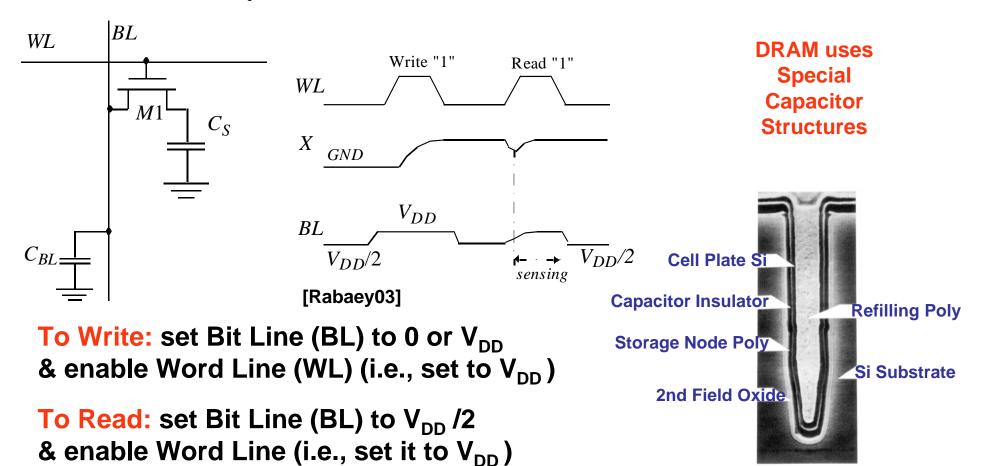
Interacting with Flash and (E)EPROM

- Reading from flash or (E)EPROM is the same as reading from SRAM
- Vpp: input for programming voltage (12V)
 - EPROM: Vpp is supplied by programming machine
 - Modern flash/EEPROM devices generate 12V using an on-chip charge pump
- · EPROM lacks a write enable
 - Not in-system programmable (must use a special programming machine)
- For flash and EEPROM, write sequence is controlled by an internal FSM
 - Writes to device are used to send signals to the FSM
 - Although the same signals are used, one can't write to flash/EEPROM in the same manner as SRAM



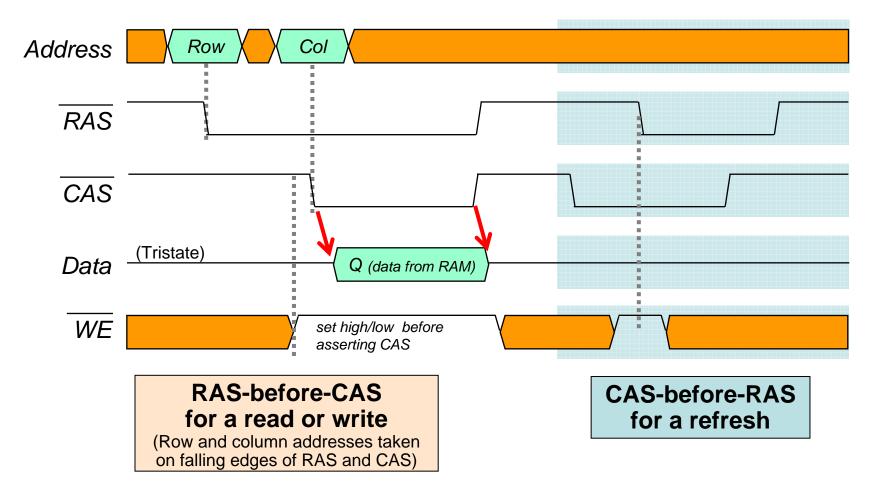
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Dynamic RAM (DRAM) Cell



- DRAM relies on charge stored in a capacitor to hold state
- Found in all high density memories (one bit/transistor)
- Must be "refreshed" or state will be lost high overhead

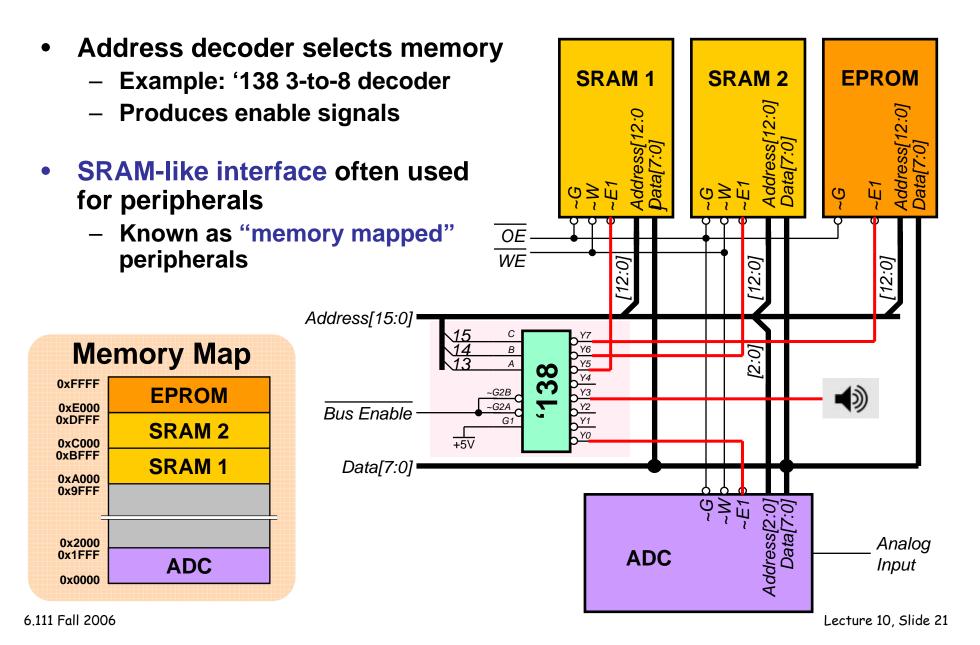
Asynchronous DRAM Operation



• Clever manipulation of RAS and CAS after reads/writes provide more efficient modes: early-write, read-write, hidden-refresh, etc.

(See datasheets for details)

5. Addressing with Memory Maps



Memory Devices: Helpful Knowledge

· SRAM vs. DRAM

- SRAM holds state as long as power supply is turned on. DRAM must be "refreshed" - results in more complicated control
- DRAM has much higher density, but requires special capacitor technology.
- FPGA usually implemented in a standard digital process technology and uses SRAM technology

Non-Volatile Memory

- Fast Read, but very slow write (EPROM must be removed from the system for programming!)
- Holds state even if the power supply is turned off

Memory Internals

- Has quite a bit of analog circuits internally -- pay particular attention to noise and PCB board integration

Device details

- Don't worry about them, wait until 6.012 or 6.374

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You Should Understand Why...

- control signals such as Write Enable should be registered
- a multi-cycle read/write is safer from a timing perspective than the single cycle read/write approach
- it is a bad idea to enable two tri-states driving the bus at the same time
- an SRAM does not need to be "refreshed" while a DRAM requires refresh
- an EPROM/EEPROM/FLASH cell can hold its state even if the power supply is turned off
- · a synchronous memory can result in higher throughput

Summary

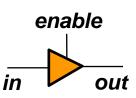
Memory Matrix Sense Amps/Drivers Column Decoder

· SRAMs:

- Use synchronous FSM for interface
- Faster than DRAM, no refresh required

· Data bus:

- Tri-state (Z) used when not driving bus
- Multiple devices can share one bus



· EEPROM:

- Useful for config. data, long-term storage
- Memory-Mapping:
 - Interact with peripheral as if it were an SRAM